

### Features & Benefits

- 2.0 W/mK Thermal Conductivity Adhesive-backed Tape
- Electrically Isolating
- Non-Silicone based formulation
- Low Interfacial Resistance
- Superior Thermal Performance

### Applications

- Power Electronics
- PCBA to heatsink
- Discrete components to heat spreader
- Fiber optics and Telecom equipment

### Introduction

**TCLAD HCA** is a thermally conductive gap filling phase change material (PCM) that is offered in a solid form with adhesive strength. The purpose of the material is to minimize thermal resistance between the heat source and the heat sink or heat spreader.

**Typical properties HCA 2.0** consists of a thermally conductive 60 °C wax based organic of thermal filler, which allows it to transform at 60 °C from solid form to a soften “wax” like material. This will allow the application to achieve minimum bond line. It is recommended to use spring clips or screws to assure constant pressure between interface and power source. It is highly recommended to retighten the screws after several power cycling in the application.

**How to use:** Remove the liner on one side and place the pad onto the first surface, PCB, component or heatsink. Remove the second liner and apply the mating surface with the required pressure as needed in the application.

**Useable life and storage:** HCA products perform best if stored in a cool and dry / non-humid environment, especially where they are not exposed to any sunlight. Typical shelf life is up to 12 months when properly stored.

**Package Information:** Typical package can be individual, or bulk packed or can be in trays or tape and reel.

**Precautions:** Please review the technical data sheet of the material before use of the product in terms of the material characteristics to fit one's application. All values stated here are typical values.

We provide custom solutions for your applications. For further inquiries, please contact your local sales agent or directly TCLAD sales in your region.

### High Conductive Adhesive

### HCA 2.0

Item	Condition	Unit	Value	Method
<b>General</b>				
Color	Visual	-	White	-
Continuous Use Temp	-	°C	-50 ~ 120	-
Thickness	Mitutoyo	Mm (mil)	0.254 (10)	-
Density	25°C	g/cc	2.8	ASTM D792
Min Bondline		µm	40	-
PCM Transition Temperature	-	°C	60	DSC
Shear Strength	25 °C	Mpa	0.7	ASTM D1002 AI/AI
Viscosity	60 °C	Pa.S	800 +/- 200	-
<b>Electrical</b>				
Flame Rating	Vertical Burn Test	-	V-0	UL94
Breakdown Voltage	AC	KV/mm	8	ASTM D149
Dielectric Constant	1 GHz	-	6.0	ASTM D150
<b>Thermal</b>				
Thermal Conductivity	-	W/m-K	2.0	ASTM D5470
RoHS	-	-	Compliant	

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Rev 2025-D88-001